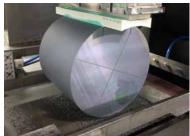




DS 261









12" WAFER WITH HIGHEST SURFACE QUALITY

- Compact and solid construction
- High thermal and vibration stability
- Lowest warp, waviness and TTV values
- Excellent results in nano-topology

PRECISE SLURRY WIRE SAW FOR HIGH END INDUSTRIES





HIGHLIGHTS DS 261

- New operator guided HMI and electrical system on Series 6 release
- Wide range of applications: silicon, quartz, gallium arsenide and other hard & brittle material in different dimensions
- Proven slurry technology and DW ready
- Optimized slurry temperature control
- 60-step recipe enables optimal process tuning
- Automated cutting process and perfect accessability
- Optional work piece orientation







Perfect alignment for highest precision



Easy operation for higher yield

| TECHNICAL DATA | DS 261 FEATURES |
|--------------------------------------|---------------------------------|
| Web length [mm] | 410 |
| Max. work piece dimensions [mm] | Ø305 mm × 400 (Ø18" on request) |
| Wire speed [m/s] | 15 (900 m/min) |
| Wire acceleration [m/s²] | 2.5 (< 6.5 s) |
| Min. wire diameter [µm] | 120 |
| Max. wire tension [N] | 50 |
| Wire guide roller axes distance [mm] | 600 |
| Cutting fluid | Slurry |
| Slurry tank [I] | 175 |
| Machine dimensions [L × W × H] [mm] | 2980 × 4120 × 3340 |
| Machine weight [kg] | 12000 |

GET IN TOUCH WITH US TODAY

TOGETHER WE WILL FIND A SOLUTION FOR YOUR REQUIREMENTS

LAPMASTER WOLTERS GMBH

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